



# PARA LIGHT ELECTRONICS CO., LTD.

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## DATA SHEET

PART NO.: LS115JFLGCT

REV: A / 0

CUSTOMER'S APPROVAL : \_\_\_\_\_

DCC : \_\_\_\_\_

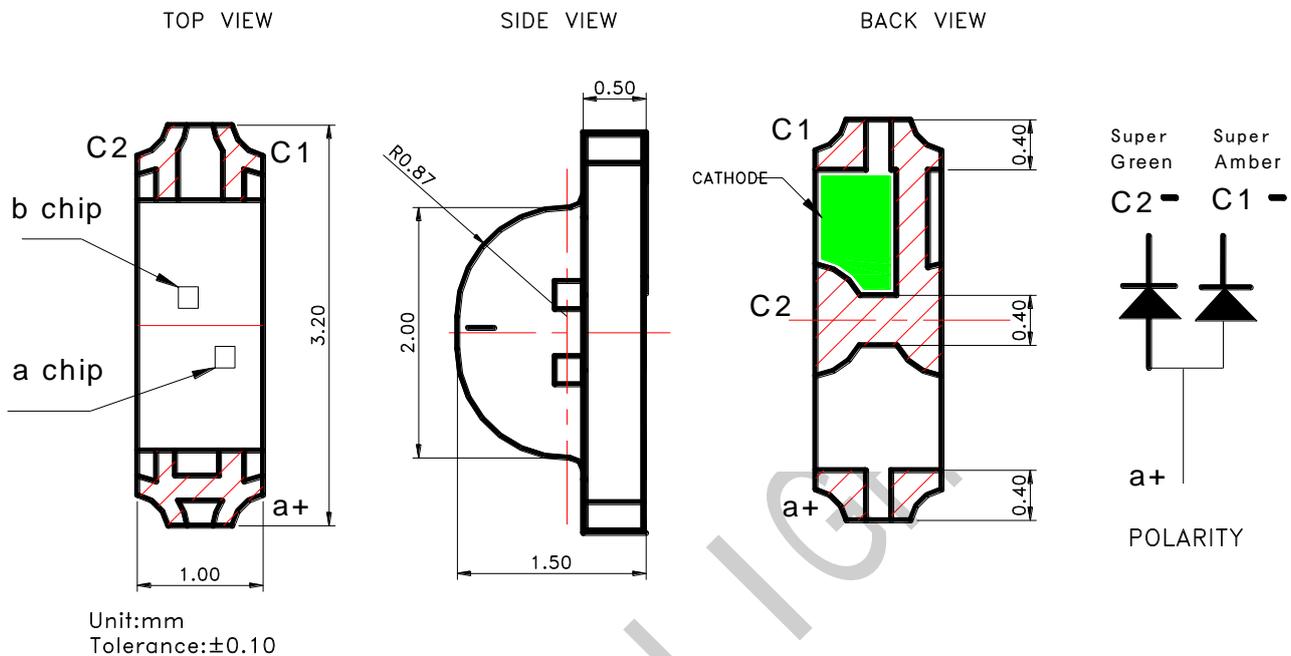
DRAWING NO. : DS-78-21-0001G

DATE : 2021-01-23

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● PACKAGE OUTLINE DIMENSIONS



Notes:

1. a chip: Super Amber; b chip: Super Green.
2. All dimensions are in millimeters.
3. Tolerance is  $\pm 0.1\text{mm}$  (.004") unless otherwise noted.

● Features

- \* Dual color, common anode, side view Chip LED.
- \* Package in 8mm tape on 7" diameter reels.
- \* Compatible with automatic Pick & Place equipment.
- \* Compatible with Reflow soldering and Wave soldering processes.
- \* EIA STD package.
- \* I.C. compatible.
- \* Pb free product.
- \* Meet RoHS Green Product.
- \* Moisture sensitivity level: 3

● **Chip Materials**

chip	Light Color	Dice Material	Lens Color
a	KF Super Amber	AlInGaP	White Clear
b	LG: Super Green	InGaN	

● **Absolute Maximum Ratings(Ta=25°C)**

Symbol	Parameter	Rating		Unit
		Super Amber	Super Green	
PD	Power Dissipation	75	100	mW
IPF	Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	80	100	mA
IF	Continuous Forward Current	30	25	mA
VR	Reverse Voltage	5	5	V
Topr	Operating Temperature Range	-40 ~ +85		°C
Tstg	Storage Temperature Range	-40 ~ +85		°C

● **Electro-Optical Characteristics(Ta=25°C)**

Parameter	Symbol	Super Amber	Super Green	Unit	Test Condition
Luminous Intensity	Min.	45.0	180.0	mcd	IF=20mA
	Typ.	100.0	600.0		
Viewing Angle	Typ. 2θ 1/2	130		deg	Note 2
Peak Wavelength	Typ. λp	611	518	nm	Measurement @Peak
Dominant Wavelength	Typ. λd	605	525	nm	IF=20mA
Spectral Line Half-Width	Typ. Δλ	17	15	nm	
Forward Voltage	Typ.	2.0	3.1	V	IF =20mA
	Max.	2.4	3.4		
Reverse Current	Max. IR	10	50	μA	VR = 5V

● **Bin Code List**

Luminous Intensity(IV), Unit:mcd@20mA					
Super Amber (a chip)			Super Green (b chip)		
Bin Code	Min	Max	Bin Code	Min	Max
P	45.0	71.0	S	180.0	280.0
Q	71.0	112.0	T	280.0	450.0
R	112.0	180.0	U	450.0	650.0
			V	650.0	900.0

Tolerance of each bin are  $\pm 15\%$

Forward Voltage(VF), Unit:V@20mA		
Super Green(b chip)		
Bin Code	Min	Max
K8	2.80	2.95
K9	2.95	3.10
K10	3.10	3.25
K11	3.25	3.40

Tolerance of each bin are  $\pm 0.1$  Volt

Dominant Wavelength (Hue),Unit: nm@20mA		
Super Green(b chip)		
Bin Code	Min	Max
AP	520	525
AQ	525	530

Tolerance of each bin are  $\pm 1$ nm

- Notes: 1.Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
2.  $\theta 1/2$  is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3.The dominant wavelength  $\lambda d$  is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4.Caution in ESD :
- Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

● **Super Amber Typical Electro-Optical Characteristics Curves**

(25°C Ambient Temperature Unless Otherwise Noted)

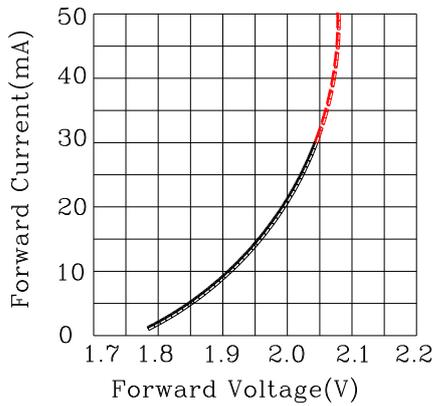


Fig.2 Forward Current vs.Forward Voltage

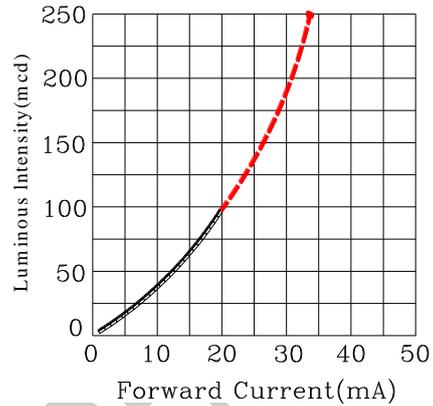


Fig.3 Luminous Intensity vs.Forward Current

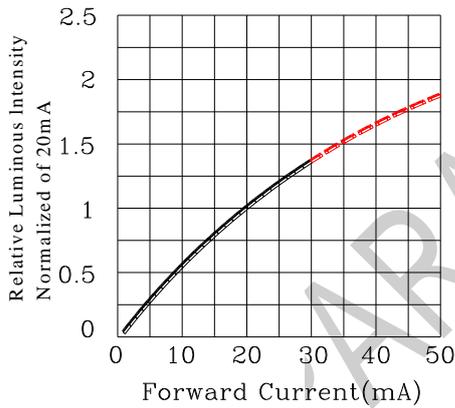


Fig.4 Relative Luminous Intensity vs.Forward Current

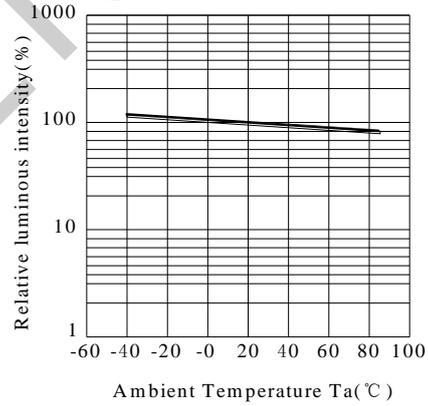


Fig.5 Luminous Intensity vs.Ambient Temperature

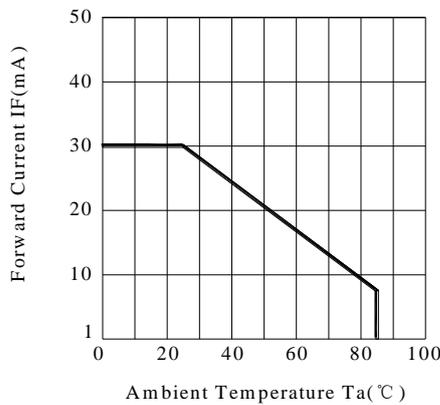


Fig.6 Forward Current Derating Curve

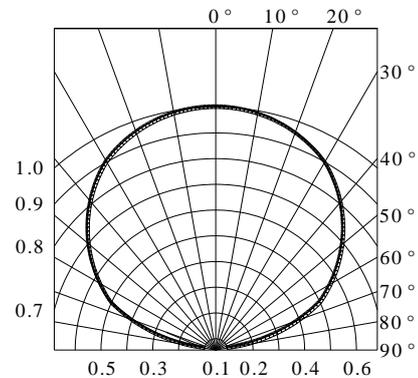


Fig.7 Relative Intensity vs.Angle

● Super Green Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

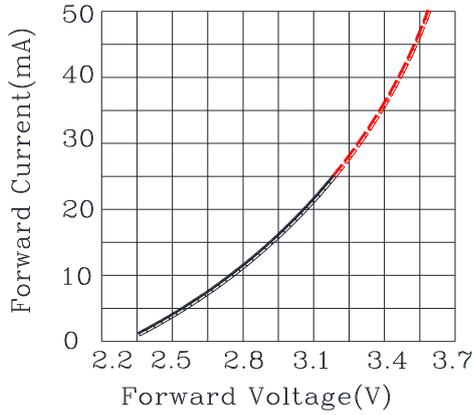


Fig.2 Forward Current vs. Forward Voltage

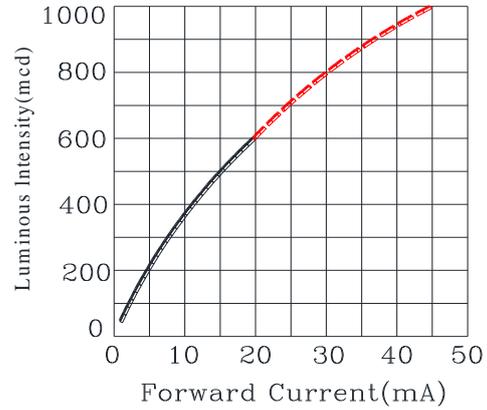


Fig.3 Luminous Intensity vs. Forward Current

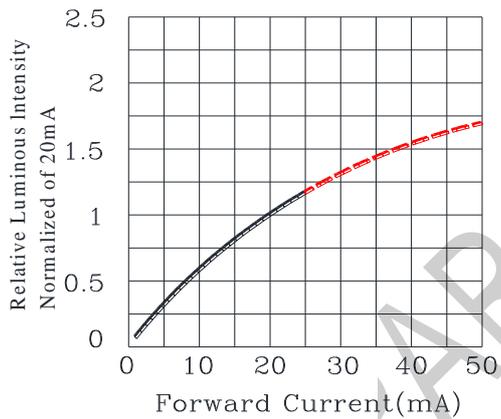


Fig.4 Relative Luminous Intensity vs. Forward Current

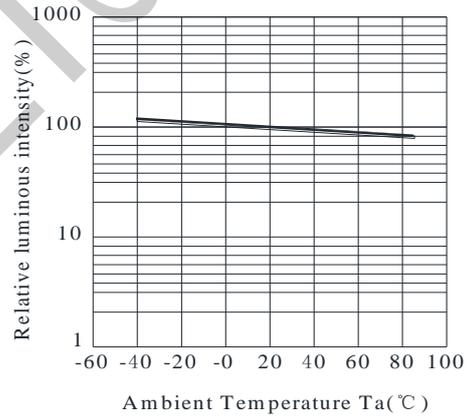


Fig.5 Luminous Intensity vs. Ambient Temperature

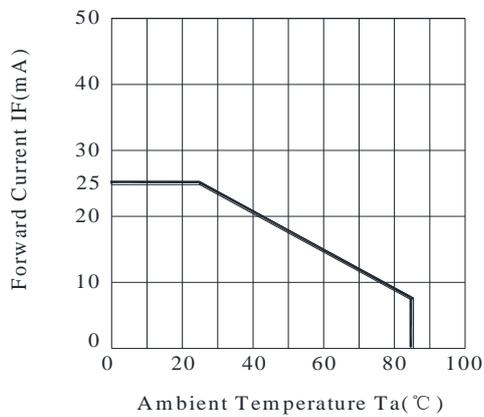


Fig.6 Forward Current Derating Curve

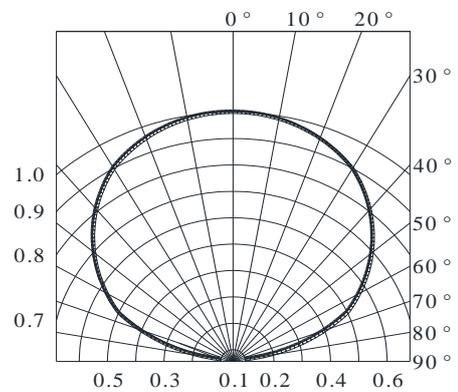


Fig.7 Relative Intensity vs. Angle



# SURFACE MOUNT DEVICE LED

Part No. : LS115JFLGCT

REV: A / 0

## ● Label Explanation



ITEM CODE: PARRA LIGHT

PART NO: LS115JFLGCT

IV --- Luminous Intensity Code

LOT NO:	<u>EM</u>	<u>S</u>	<u>L</u>	<u>12</u>	<u>09</u>	<u>0110</u>
	A	B	C	D	E	F

A---EM: Emos Code

B---S:SMD

L---Local

D---Year

E---Month

F---SPEC.

PACKING QUANTITY OF BAG :

3000pcs for 150、170、110、155、115 series

4000pcs for 191 series

5000pcs for 192 series

DATE CODE:	<u>2012</u>	<u>09</u>	<u>10</u>
	G	H	I

G--- Year

H--- Month

I --- Day

● Typical Electro-Optical Characteristics Curves

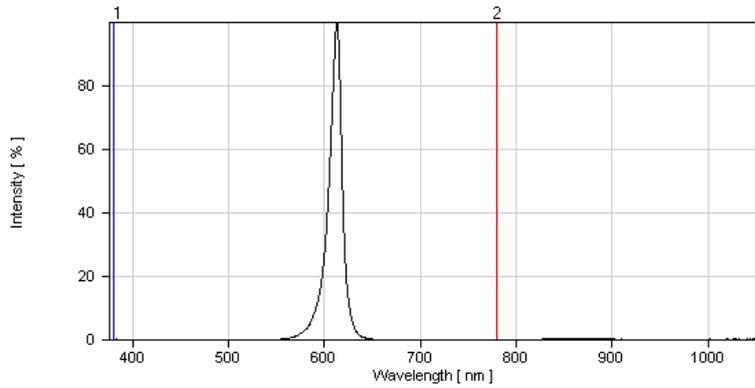


Fig.1 Super Amber Relative Intensity vs. Wavelength

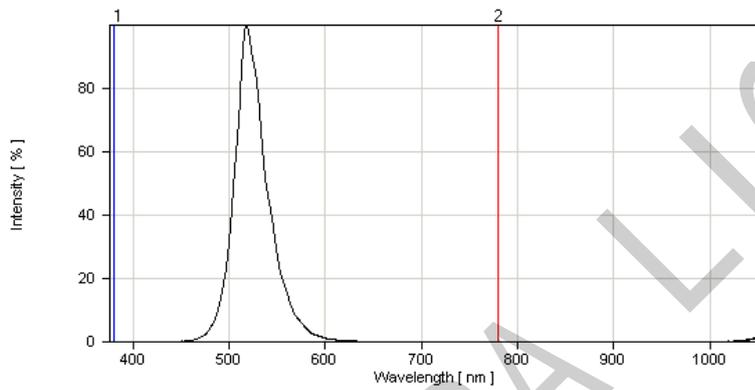
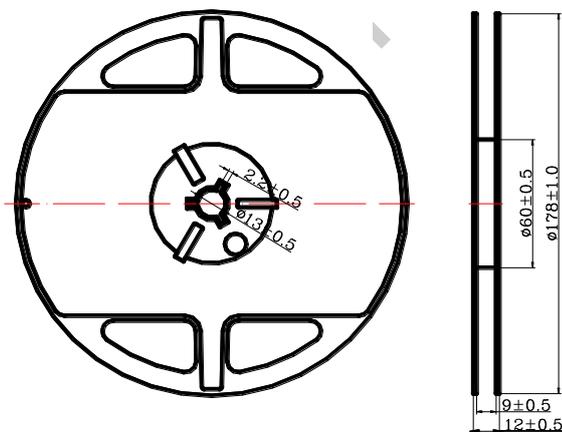


Fig.2 Super Green Relative Intensity vs. Wavelength

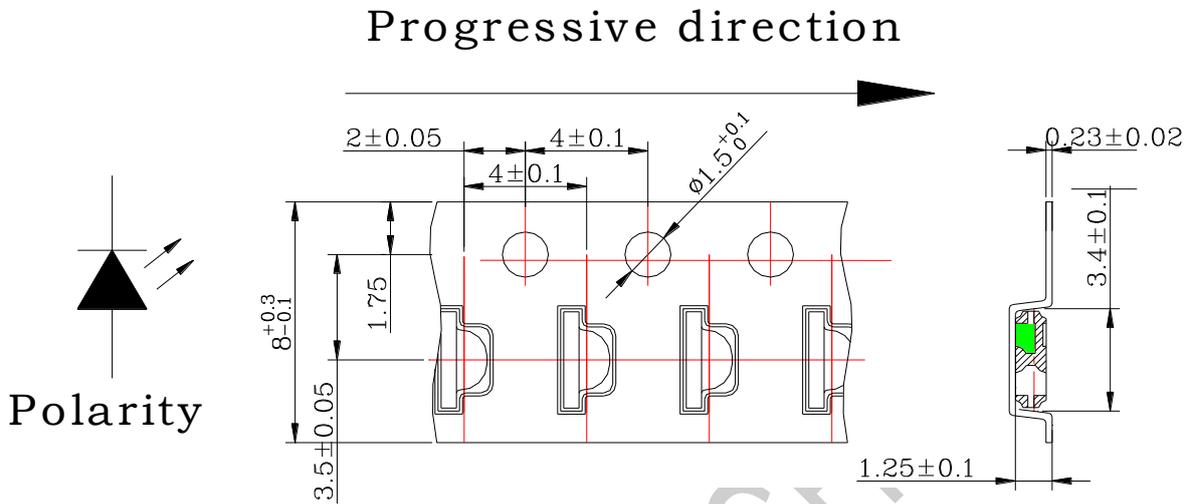
● Reel Dimensions



Notes:

1. Taping Quantity : 3000pcs
2. The tolerances unless mentioned is  $\pm 0.1\text{mm}$ , Angle  $\pm 0.5^\circ$  , Unit : mm.

● Package Dimensions Of Tape And Reel

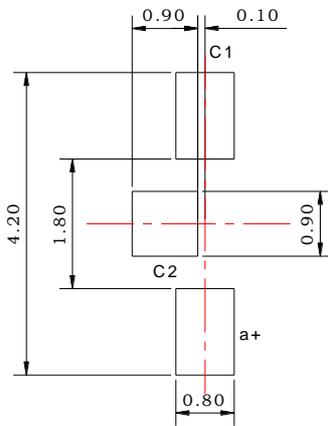


Notes : All dimensions are in millimeters.

● Cleaning

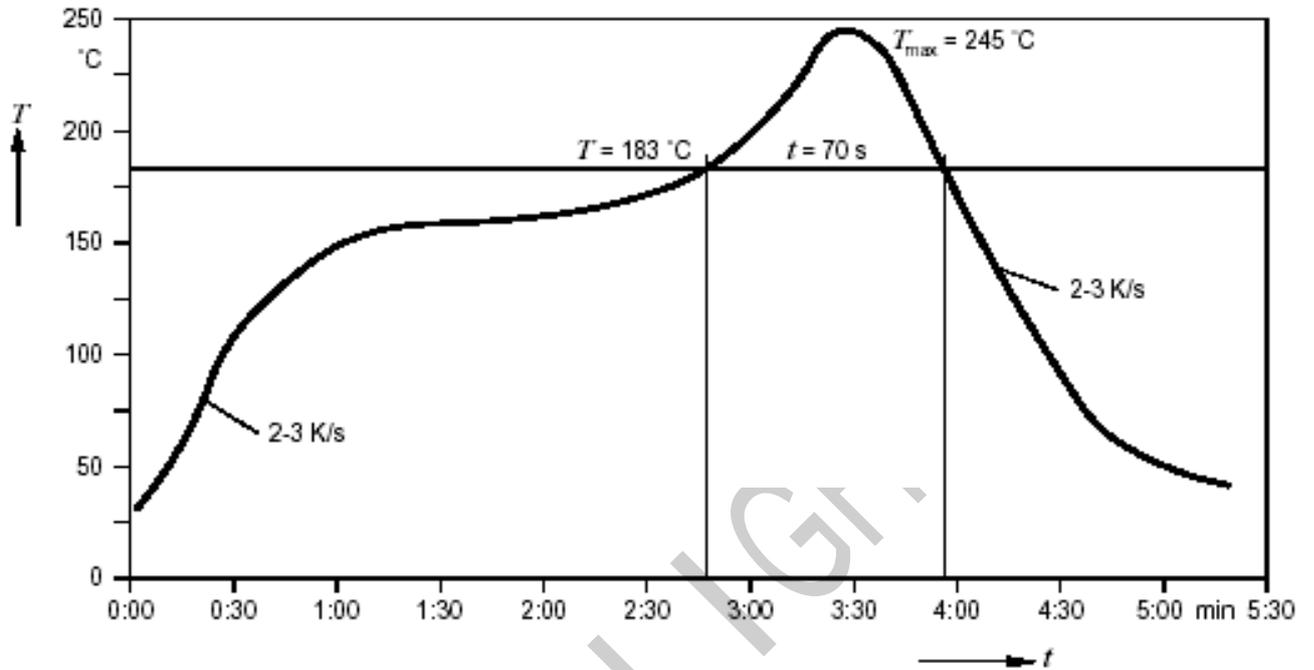
- \* If cleaning is required , use the following solutions for less than 1 minute and less than 40°C.
- \* Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- \* Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

● Suggest Soldering Pad Dimensions

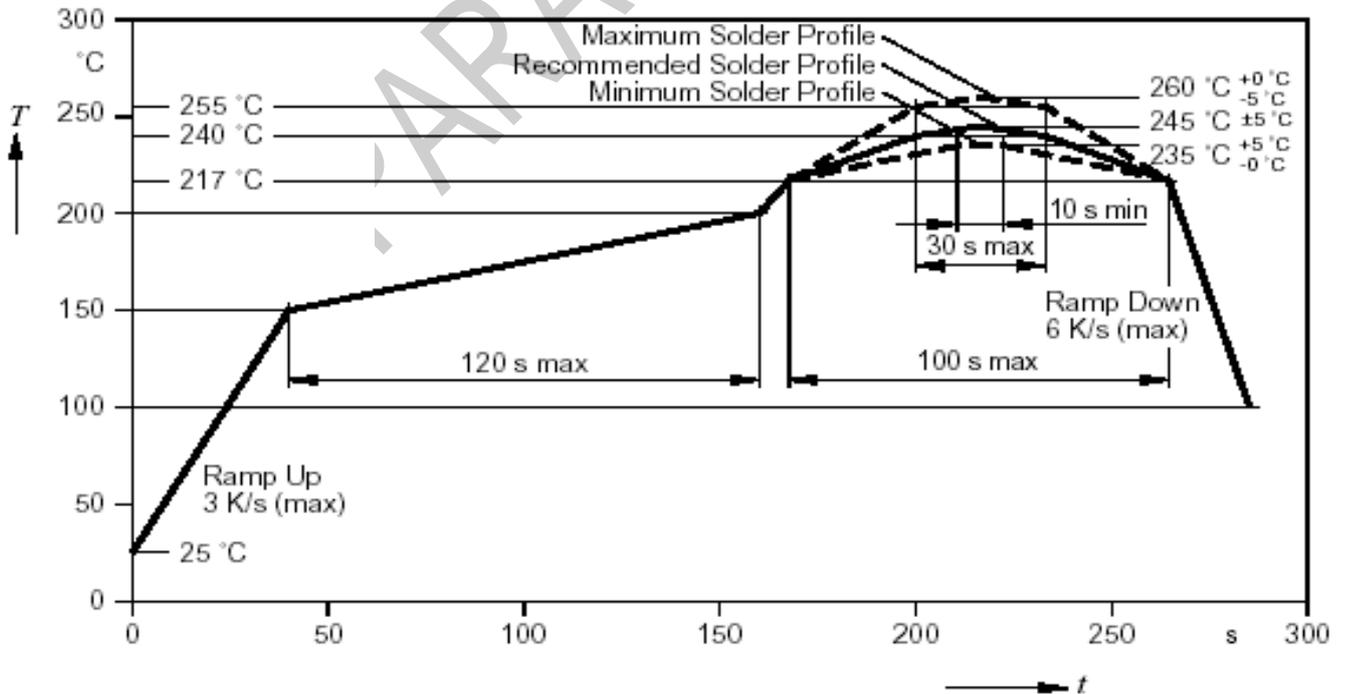


Direction of PWB camber  
and go to reflow furnace

● Suggest Sn/Pb IR Reflow Soldering Profile Condition:



● Suggest Pb-Free IR Reflow Soldering Profile Condition:



**● CAUTIONS****1.Application Limitation :**

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application). Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

**2.Storage :**

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment:  $60 \pm 5^{\circ}\text{C}$  for 24 hours

3.Soldering(Standard Process) :

Do not apply any stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering condition.

Reflow Soldering :

Pre-heat 120~150 °C, 120sec. MAX., Peak temperature : 240 °C Max. Soldering time : 10 sec Max.

Soldering Iron : (Not recommended)

Temperature 300 °C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.

Wave soldering :

Pre-heat 100 °C Max, Pre-heat time 60s Max, Solder wave 260 °C Max, Soldering time 5 sec. Max.

performed consecutively cooling process is required between 1st and 2nd soldering processes.

4. Lead-Free Soldering

For Reflow Soldering :

- 1、 Pre-Heat Temp : 150-180°C,120sec.Max.
- 2、 Soldering Temp : Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3、 Peak Temperature : 260°C , 5sec.
- 4、 Reflow Repetition : 2 Times Max.
- 5、 Suggest Solder Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu

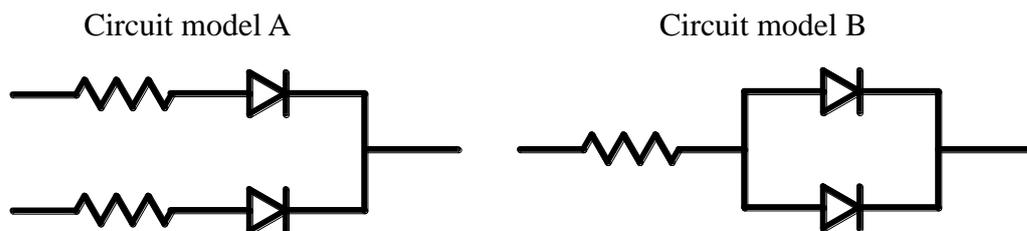
For Soldering Iron (Not Recommended) :

- 1、 Iron Tip Temp : 350°C Max.
- 2、 Soldering Iron : 30w Max.
- 3、 Soldering Time : 3 Sec. Max. One Time.

For Dip Soldering :

- 1、 Pre-Heat Temp : 150°C Max. 120 Sec. Max.
- 2、 Bath Temp : 265°C Max.
- 3、 Dip Time : 5 Sec. Max.

5. Drive Method



(A)Recommended circuit.

(B)The difference of brightness between LED`s could be found due to the Vf-If characteristics of LED.